

RILSAN® BESNO MED

PA11,EHL,22-010
Rilsan® BESNO MED树脂 是一种采用可再生材料制成的聚酰胺11。该牌号专用于挤出，带来最佳质量，而且专门设计可达到微创器械等严格的医疗应用要求。
应要求可提供 USP 第VI 类合规证明书。

性能	干 / 已调节	单位	测试标准
机械性能			
拉伸模量	- / 1200	MPa	ISO 527-1/-2
	- / 174000	psi	
屈服应力	- / 40	MPa	ISO 527-1/-2
	- / 5800	psi	
屈服伸长率	- / 6	%	ISO 527-1/-2
名义断裂伸长率	- / >50	%	ISO 527-1/-2
肖氏硬度D, 15 s	71 / *	-	ISO 868
简支梁冲击强度, +23°C	- / 无断裂	kJ/m²	ISO 179/1eU
简支梁冲击强度, -30°C	- / 无断裂	kJ/m²	ISO 179/1eU
简支梁缺口冲击强度, +23°C	- / 15	kJ/m²	ISO 179/1eA
	- / 7.14	ftlb/in²	
简支梁缺口冲击强度, -30°C	- / 13	kJ/m²	ISO 179/1eA
	- / 6.18	ftlb/in²	
热性能			
熔融温度, 10°C/min	186 / *	°C	ISO 11357-1/-3
其它性能			
密度	1020 / 1020	kg/m³	ISO 1183
	1.02 / 1.02	g/cm³	

- 主要应用

—医用管路

—导管
- 包装

该牌号的供货规格为干燥型密封包装（44磅袋装），可以随时加工处理。

保质期

自发货之日起2年。有关过期使用的任何事宜，请咨询我司技术服务人员。

加工条件：

—推荐熔融温度（最小值/建议值/最大值）：230°C/250°C/280°C.

—干燥时间和温度（只有包装袋打开2小时以上时才有必要干燥）：4-8小时，65-80°C。

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加工方法 异型材挤出成型, 其它挤出成型	Headquarters: Arkema France 420 rue d'Estienne d'Orves 92705 Colombes Cedex France T +33 (0)1 49 00 80 80 hpp.arkema.com Arkema Inc. – High Performance Polymers 900 First Avenue King of Prussia, PA 19406 Tel.: +1 610 205 7000 hpp.arkema.com
供货形式 粒料	
特殊性能 生物基	
地区供应 北美, 欧洲, 亚太, 中南美洲, 中东/非洲	

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